505502198 05/31/2019

# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Yoshiharu Hirakata	08/02/2016

### **RECEIVING PARTY DATA**

Name:	SEMICONDUCTOR ENERGY LABORATORY CO., LTD.
Street Address:	398, HASE
City:	ATSUGI-SHI, KANAGAWA-KEN
State/Country:	JAPAN
Postal Code:	243-0036

## **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	16426132

### **CORRESPONDENCE DATA**

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: (202) 783-5070 Email: apsi@fr.com

**Correspondent Name:** JOHN F. HAYDEN

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ATTORNEY DOCKET NUMBER:	12732-1729002
NAME OF SUBMITTER:	SHARON M. ALLEN
SIGNATURE:	/Sharon M. Allen/
DATE SIGNED:	05/31/2019

**Total Attachments: 1** 

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**REEL: 049327 FRAME: 0739** 505502198

**PATENT** 

# **ASSIGNMENT**

For valuable consideration, I, <u>Yoshiharu HIRAKATA of Tochigi, Tochigi, Japan</u> hereby assign to <u>Semiconductor Energy Laboratory Co., Ltd.</u>, a <u>Japanese</u> corporation having a place of business at:

398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and
interest throughout the world in the inventions and improvements which are subject of an application for
United States Patent signed by me this day, entitled INFORMATION PROCESSING DEVICE,
filed August 9, 2016 , and assigned U.S. Serial Number 15/231,965 , and I authorize
and request the Assignee or the attorneys appointed in said application to hereafter complete this assignment
by inserting above the filing date and serial number of said application when known; this assignment
including said application, any and all United States and foreign patents, utility models, and design
registrations granted for any of said inventions or improvements, and the right to claim priority based on the
filing date of said application under the International Convention for the Protection of Industrial Property,
the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and I
authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models,
design registrations and like rights of exclusion and for inventors' certificates for said inventions and
improvements; and I agree for myself and my respective heirs, legal representatives and assigns, without
further compensation to perform such lawful acts and to sign such further applications, assignments,
Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate
fully this assignment.

Signature

**RECORDED: 05/31/2019** 

Name:

Yoshiharu HIRAKATA

Date:  $\frac{\partial R}{\partial R} = \frac{\partial R}{\partial$ 

PATENT REEL: 049327 FRAME: 0740